Dual 2-Input NOR Gate

The NL27WZ02 is a high performance dual 2-input NOR Gate operating from a 1.65 V to 5.5 V supply.

Features

- Extremely High Speed: t_{PD} 2.5 ns (typical) at $V_{CC} = 5.0 \text{ V}$
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability With 5.0 V TTL Logic with V_{CC} = 3.0 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Replacement for NC7WZ02
- Chip Complexity: FET = 112
- These Devices are Pb-Free and are RoHS Compliant

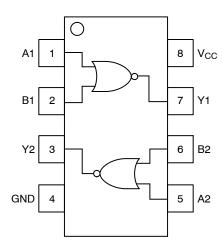


Figure 1. Pinout

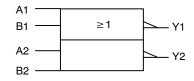


Figure 2. Logic Symbol



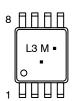
ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM



US8 US SUFFIX CASE 493



L3 = Specific Device Code

M = Date Code*= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

PIN ASSIGNMENT

Pin	Function
1	A1
2	B1
3	Y2
4	GND
5	A2
6	B2
7	Y1
8	V _{CC}

FUNCTION TABLE

Inp	out	Output Y = A + B
Α	В	Y
L	L	Н
L	Н	L
Н	L	L
Н	Н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Units
V _{CC}	DC Supply Voltage		-0.5 to +7.0	٧
VI	DC Input Voltage		-0.5 to +7.0	٧
V _O	DC Output Voltage		-0.5 to +7.0	٧
I _{IK}	DC Input Diode Current	V _I < GND	-50	mA
l _{ok}	DC Output Diode Current	V _O < GND	-50	mA
Ι _Ο	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
I _{GND}	DC Ground Current per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 1)		250	°C/W
P _D	Power Dissipation in Still Air at 85°C		250	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 34		UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)		> 2000 > 200 N/A	V
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125°C (Note 5)		±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Units
Supply Voltage Operating Data Retention Only	V _{CC}	1.65 1.5	5.5 5.5	V
Input Voltage (Note 6)	VI	0	5.5	V
Output Voltage (HIGH or LOW State)	V _O	0	5.5	V
Operating Free-Air Temperature	T _A	-55	+125	°C
Input Transition Rise or Fall Rate $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$ $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	Δt/ΔV	0 0 0 0	20 20 10 5	ns/V

^{6.} Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

DC ELECTRICAL CHARACTERISTICS

			V_{CC} $T_A = 25^{\circ}C$ $-55^{\circ}C \le T_A \le 125$		Voc	T _A = 25°C		A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input Voltage		1.65 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{OH}	High-Level Output Voltage V _{IN} = V _{IL} or V _{IH}	$\begin{split} I_{OH} &= -100 \ \mu A \\ I_{OH} &= -4 \ mA \\ I_{OH} &= -8 \ mA \\ I_{OH} &= -12 \ mA \\ I_{OH} &= -16 \ mA \\ I_{OH} &= -24 \ mA \\ I_{OH} &= -32 \ mA \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V _{CC} 1.5 2.1 2.4 2.7 2.5 4.0		V _{CC} - 0.1 1.29 1.90 2.20 2.40 2.30 3.80		V
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IH} or V _{OH}	$\begin{split} I_{OL} &= 100 \ \mu\text{A} \\ I_{OL} &= 4 \ \text{mA} \\ I_{OL} &= 8 \ \text{mA} \\ I_{OL} &= 12 \ \text{mA} \\ I_{OL} &= 16 \ \text{mA} \\ I_{OL} &= 24 \ \text{mA} \\ I_{OL} &= 32 \ \text{mA} \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.0 0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0			1		10	μΑ
Icc	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5			1		10	μΑ

AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 3.0 \text{ ns}$

			V _{CC}	V _{CC} T _A = 25°C		-55°C ≤ T	_A ≤ 125°C		
Parameter	Condition	Symbol	(V)	Min	Тур	Max	Min	Max	Units
Propagation Delay	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	t _{PLH}	1.8 ± 0.15	2.0	7.4	9.5	2.0	9.7	ns
(Figure 3 and 4)		t _{PHL}	2.5 ± 0.20	1.2	3.3	5.4	1.2	5.8	
	$\begin{aligned} R_L &= 1 \text{ M}\Omega, C_L = 15 \text{ pF} \\ R_L &= 500 \ \Omega, C_L = 50 \text{ pF} \end{aligned}$		3.3 ± 0.30	0.8 1.2	2.6 3.2	3.9 4.8	0.8 1.2	4.3 5.2	
	$\begin{aligned} R_L &= 1 \text{ M}\Omega, C_L = 15 \text{ pF} \\ R_L &= 500 \Omega, C_L = 50 \text{ pF} \end{aligned}$		5.0 ± 0.50	0.5 0.8	1.9 2.5	3.1 3.7	0.5 0.8	3.3 4.0	

CAPACITIVE CHARACTERISTICS

Parameter	Condition	Symbol	Typical	Units
Input Capacitance	V _{CC} = 5.5 V, V _I = 0 V or V _{CC}	C _{IN}	2.5	pF
Power Dissipation Capacitance (Note 7)	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC} 10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	C _{PD}	9.0 11.0	pF

^{7.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

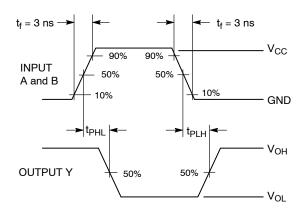
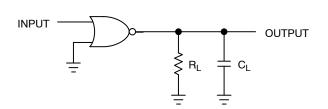


Figure 3. Switching Waveform



A 1–MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

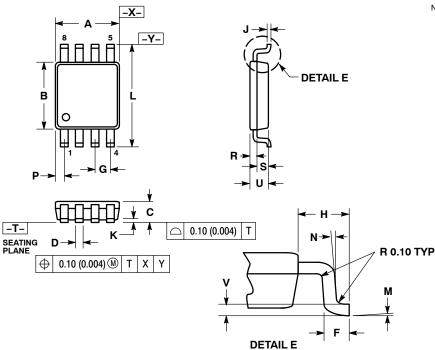
ORDERING INFORMATION

Device	Package	Shipping [†]
NL27WZ02USG	US8 (Pb-Free)	3000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

US8 CASE 493-02 **ISSUE B**

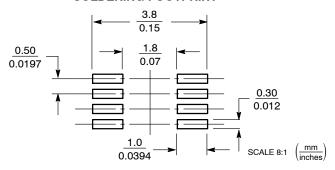


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- ANSI 114-3W, 1962. CONTROLLING DIMENSION: MILLIMETERS. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH. PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.140 MM
- DIMENSION "B" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTER-LEAD FLASH AND PROTRUSION. SHALL NOT E3XCEED 0.140 (0.0055") PER SIDE.
- LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM.
- (300-800 "). ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508 (0.0002 ").

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.90	2.10	0.075	0.083
В	2.20	2.40	0.087	0.094
С	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50	BSC	0.020	BSC
Н	0.40	REF	0.016	REF
J	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.20	0.118	0.126
М	0 °	6°	0 °	6°
N	5 °	10 °	5 °	10 °
Р	0.23	0.34	0.010	0.013
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
V	0.12 BSC		0.005	BSC

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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